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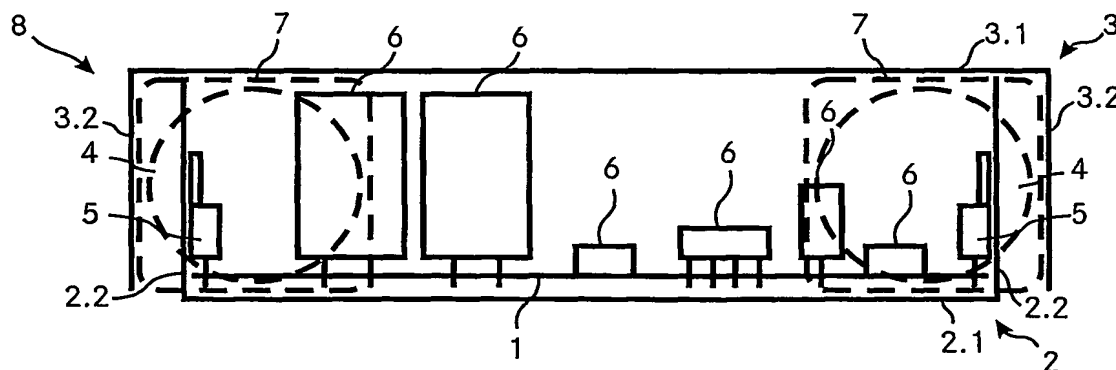
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- (75) Inventor/Applicant (*for US only*): SCHWAB, Markus [CH/CH]; Brünnenrain 21, CH-3284 Fräschels (CH). For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: POWER SUPPLY WITH IMPROVED COOLING



(57) Abstract: The casing of a power supply (8) includes a bottom (2) and a cover (3). Both of them have a U-like shape. Since the cover (3) is slightly wider than the bottom (2) two air ducts (4) are provided between the side plates (2.2) of the bottom (2) and the corresponding side plates (3.2) of the cover (3) respectively. A printed circuit board (1) is mounted within the casing, particularly on the bottom (2). Different mechanical, electric and/or electronic components (6) are mounted on the printed circuit board (1). Furthermore, heat generating components (5) are mounted on the printed circuit board (1) such that they are in tight contact with the side plates (2.2) of the bottom (2). The waste heat generated by the components (5) is transferred to the side plates (2.2) of the bottom (2) and further on to the cover (3) and its side plates (3.2). From there the heat is dissipated into the air and particularly into the air ducts (4) from where it is dissipated by the air flow from two fans (7) that are arranged at the inlet of the air ducts (4).

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